L Number	Hits	Search Text	DB	Time stamp
1	1	("5849608").PN.	USPAT	2004/11/05 18:36
2	28	polyimide near (encapsulant or encapsulate)	USPAT	2004/11/05 18:36
3	34	polyimide near (encapsulant or encapsulate)	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/11/05 18:37
4	21	(polyimide near (encapsulant or encapsulate)) and (@ad<19970804)	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/11/05 18:42
5	160	257/666.ccls. and (@ad<19970804) and (encapsualnt or encapsulate or resin or silicone or mold or molding) and (ball or bump or balls)	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/11/05 18:43
6	165	257/666.ccls. and (@ad<19970804) and (encapsulant or encapsulate or resin or silicone or mold or molding) and (ball or bump or balls)	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/11/05 18:45
7	175	257/666.ccls. and (@ad<19970804) and (encapsulant or encapsulate or resin or silicone or mold or molding or plastic) and (ball or bump or balls)	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/11/05 19:25
8	17	5849608.URPN.	USPAT	2004/11/05 18:46
9	1	("5849608")..PN.	USPAT	2004/11/05 18:57
10	98	257/666.ccls. and (@ad<19950508) and (encapsulant or encapsulate or resin or silicone or mold or molding or plastic) and (ball or bump or balls)	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/11/05 19:26
11	12491	(chip or die) and (@ad<19950508) and (encapsulant or encapsulate or resin or silicone or mold or molding or plastic) and (ball or bump or balls)	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/11/05 19:22
12	5222	((chip or die) and (@ad<19950508) and (encapsulant or encapsulate or resin or silicone or mold or molding or plastic) and (ball or bump or balls)) and (lead or leads)	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/11/05 19:23
13	1969	((chip or die) and (@ad<19950508) and (encapsulant or encapsulate or resin or silicone or mold or molding or plastic) and (ball or bump or balls)) and ((lead or leads) with ((chip or die) or (ball or bump or balls or bumps)))	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/11/05 19:24
14	30778	(((chip or die) and (@ad<19950508) and (encapsulant or encapsulate or resin or silicone or mold or molding or plastic) and (ball or bump or balls)) and ((lead or leads) with ((chip or die) or (ball or bump or balls or bumps)))) nt (257/666.ccls. and (@ad<19970804) and (encapsulant or encapsulate or resin or silicone or mold or molding or plastic) and (ball or bump or balls))	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/11/05 19:24
15	1885	(((chip or die) and (@ad<19950508) and (encapsulant or encapsulate or resin or silicone or mold or molding or plastic) and (ball or bump or balls)) and ((lead or leads) with ((chip or die) or (ball or bump or balls or bumps)))) not (257/666.ccls. and (@ad<19970804) and (encapsulant or encapsulate or resin or silicone or mold or molding or plastic) and (ball or bump or balls))	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/11/05 19:24

16	1219	((chip or die) and (@ad<19950508) and (encapsulant or encapsulate or resin or silicone or mold or molding or plastic) and (ball or bump or balls)) and ((lead or leads) with (ball or bump or balls or bumps))	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/11/05 19:24
17	1163	(((chip or die) and (@ad<19950508) and (encapsulant or encapsulate or resin or silicone or mold or molding or plastic) and (ball or bump or balls)) and ((lead or leads) with (ball or bump or balls or bumps))) not (257/666.ccls. and (@ad<19970804) and (encapsulant or encapsulate or resin or silicone or mold or molding or plastic) and (ball or bump or balls))	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/11/05 19:26
18	156	257/738.ccls. and (@ad<19970804) and (encapsulant or encapsulate or resin or silicone or mold or molding or plastic) and (lead or leads)	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/11/05 19:30
19	142	(257/738.ccls. and (@ad<19970804) and (encapsulant or encapsulate or resin or silicone or mold or molding or plastic) and (lead or leads)) not (257/666.ccls. and (@ad<19970804) and (encapsulant or encapsulate or resin or silicone or mold or molding or plastic) and (ball or bump or balls))	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/11/05 19:35
20	52	((257/738.ccls. and (@ad<19970804) and (encapsulant or encapsulate or resin or silicone or mold or molding or plastic) and (lead or leads)) not (257/666.ccls. and (@ad<19970804) and (encapsulant or encapsulate or resin or silicone or mold or molding or plastic) and (ball or bump or balls))) and (@ad<19950508)	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/11/05 19:28
21	1969	(((chip or die) and (@ad<19950508) and (encapsulant or encapsulate or resin or silicone or mold or molding or plastic) and (ball or bump or balls)) and ((lead or leads) with ((chip or die) or (ball or bump or balls or bumps)))) and (@ad<19950508)	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/11/05 19:30
22	102	257/734.ccls. and (@ad<19970804) and (encapsulant or encapsulate or resin or silicone or mold or molding or plastic) and (lead or leads)	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/11/05 19:31
23	85	(257/734.ccls. and (@ad<19970804) and (encapsulant or encapsulate or resin or silicone or mold or molding or plastic) and (lead or leads)) and (@ad<19950508)	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/11/05 19:30
24	128	257/780.ccls. and (@ad<19970804) and (encapsulant or encapsulate or resin or silicone or mold or molding or plastic) and (lead or leads)	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/11/05 19:30
25	59	(257/780.ccls. and (@ad<19970804) and (encapsulant or encapsulate or resin or silicone or mold or molding or plastic) and (lead or leads)) and (@ad<19950508)	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/11/05 19:31
26	193	257/737.ccls. and (@ad<19970804) and (encapsulant or encapsulate or resin or silicone or mold or molding or plastic) and (lead or leads)	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/11/05 19:31
27	87	(257/737.ccls. and (@ad<19970804) and (encapsulant or encapsulate or resin or silicone or mold or molding or plastic) and (lead or leads)) and (@ad<19950508)	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/11/05 19:31
28	63	438/612.ccls. and (@ad<19970804) and (encapsulant or encapsulate or resin or silicone or mold or molding or plastic) and (lead or leads)	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/11/05 19:33

29	35	(438/612.ccls. and (@ad<19970804) and (encapsulant or encapsulate or resin or silicone or mold or molding or plastic) and (lead or leads)) and (@ad<19950508)	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/11/05 19:32
30	122	438/123.ccls. and (@ad<19970804) and (encapsulant or encapsulate or resin or silicone or mold or molding or plastic) and (ball or bump or balls or bumps)	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/11/05 19:33
31	66	438/123.ccls. and (@ad<19950508) and (encapsulant or encapsulate or resin or silicone or mold or molding or plastic) and (ball or bump or balls or bumps)	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/11/05 19:35
32	31	438/124.ccls. and (@ad<19950508) and (encapsulant or encapsulate or resin or silicone or mold or molding or plastic) and (ball or bump or balls or bumps)	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/11/05 19:36
33	21	(438/124.ccls. and (@ad<19950508) and (encapsulant or encapsulate or resin or silicone or mold or molding or plastic) and (ball or bump or balls or bumps)) not (438/123.ccls. and (@ad<19950508) and (encapsulant or encapsulate or resin or silicone or mold or molding or plastic) and (ball or bump or balls or bumps))	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/11/05 19:36
34	40	438/15.ccls. and (@ad<19950508) and (encapsulant or encapsulate or resin or silicone or mold or molding or plastic) and (ball or bump or balls or bumps)	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/11/05 19:37
35	3	438/22.ccls. and (@ad<19950508) and (encapsulant or encapsulate or resin or silicone or mold or molding or plastic) and (ball or bump or balls or bumps)	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/11/05 19:38
36	18	438/122.ccls. and (@ad<19950508) and (encapsulant or encapsulate or resin or silicone or mold or molding or plastic) and (ball or bump or balls or bumps)	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/11/05 19:42
37	14	438/111.ccls. and (@ad<19950508) and (encapsulant or encapsulate or resin or silicone or mold or molding or plastic) and (ball or bump or balls or bumps)	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/11/05 19:42